



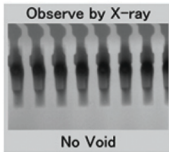
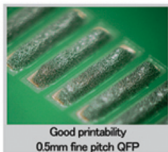
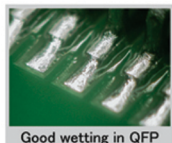
For  
LIGHT  
EMITTING  
DIODE  
(LEDs)

Saru Ishikawa provides a range of solder materials for Light Emitting Diode (LED) manufacturing

## SOLDER PASTE

### Excellent Wettability

BH63K878DH

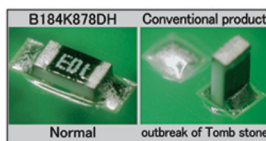


- Good Wettability, no void because flux have high stable power.
- Good Printability.

### Tin Lead

### Prevention Tomb Stone

B184K878DH

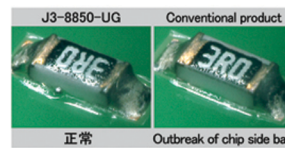


- Wide range of melting point, so that control Tomb stone



### For Chip Side Ball J3-8850-UG

Comparison of Chip Side Ball

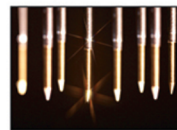


- Ultra Low Voiding.
- Clear Residue.
- Good Wettability because Solder powder can not oxidized easily.
- No Chip side ball because flux have for resistance power.

### Lead Free

### For ICT J3-8852-UG

Comparison of Chip Side Ball



- Flux residue is softer, so that reduce ICT error numbers.
- High Electric Reliability



## FLUX CORE SOLDER WIRE

### SUPER ROSIN 60/63LXB

Tin Lead  
MIL-RA  
IPC-ROH1  
ISO-1.1.2.Y  
JIS-B



- Good activated power & high wettability speed Low spattering
- Less smoke & smell
- High speed soldering by Robotic machine.

### EVASOL J3-MKT-3

Lead Free  
MIL-RMA  
IPC-ROL1  
ISO-1.1.2.X  
JIS-A



- Good activated power & high wettability speed
- Low spattering
- Less smoke & smell.